

104-13-304-41-780000

104-13-304-41-780000 Information

Heisener.com	Part Number Manufacturer Category Description Package	104-13-304-41-780000 Mill-Max Manufacturing Corp. Connectors, Interconnects Sockets for ICs, Transistors CONN IC DIP SOCKET 4POS GOLD - For the pricing/inventory/lead time, please contact	
For Reference Only		us Website: https://www.heisener.com E-mail: salesdept@heisener.com	Request a Quote

Certified Quality

Heisener's commitment to quality has shaped our processes for sourcing, testing, shipping, and every step in between. This foundation underlies each component we sell.



104-13-304-41-780000 Specifications

Manufacturer Part Number	104-13-304-41-780000
Manufacturer	Mill-Max Manufacturing Corp.
Category	Connectors, Interconnects
	Sockets for ICs, Transistors
Package	-
Series	104
Туре	DIP, 0.3" (7.62mm) Row Spacing
Number of Positions or Pins (Grid)	4 (2 x 2)
Pitch - Mating	0.100" (2.54mm)
Contact Finish - Mating	Gold
Contact Finish Thickness - Mating	30µin (0.76µm)
Contact Material - Mating	Beryllium Copper
Mounting Type	Through Hole
Features	Open Frame
Termination	Press-Fit
Pitch - Post	0.100" (2.54mm)
Contact Finish - Post	Gold
Contact Finish Thickness - Post	10µin (0.25µm)
Contact Material - Post	Brass Alloy
Housing Material	Thermoplastic
Operating Temperature	-
	Report errors?

104-13-304-41-780000 Guarantees



Quality Guarantees

We provide 90 days warranty. * If the items you received were not in perfect quality, we would be responsible for your refund or replacement, but the items must be returned in their original condition.

SERVICE EVARANTEE

Service Guarantees

We guarantee 100% customer satisfaction. Our experienced sales team and tech support team back our services to satisfy all our customers.

DISCOVER

104-13-304-41-780000 Payment Methods WIRE transfer PayPal Methods 104-13-304-41-780000 Shipping Methods



If you have any question about 104-13-304-41-780000, please do not hesitate to contact us! Website: https://www.heisener.com E-mail: salesdept@heisener.com